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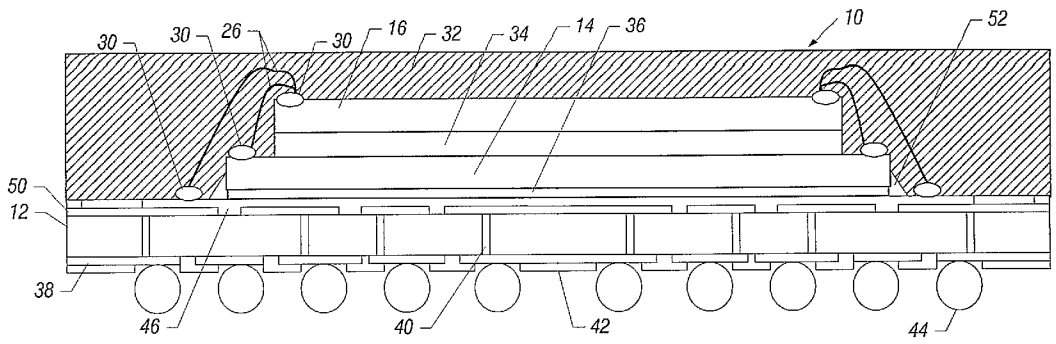
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(54) **Title:** PACKAGING LOGIC AND MEMORY INTEGRATED CIRCUITS



(57) **Abstract:** Logic and memory may be packaged together in a single integrated circuit package that, in some embodiments, has high input/output pin count and low stack height. In some embodiments, the logic may be stacked on top of the memory which may be stacked on a flex substrate. Such a substrate may accommodate a multilayer interconnection system which facilitates high pin count and low package height. In some embodiments, the package may be wired so that the memory may only be accessed through the logic.

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